DA2J107

Silicon epitaxial planar type

For speed switching circuits
DA3X107K in SMini2 type package

■ Features

- High reverse voltage V_R
- Small reverse current I_R
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  SMini2-F5-B
- Pin Name
  1: Cathode
  2: Anode

■ Marking Symbol: B1

■ Absolute Maximum Ratings $T_a = 25°C$

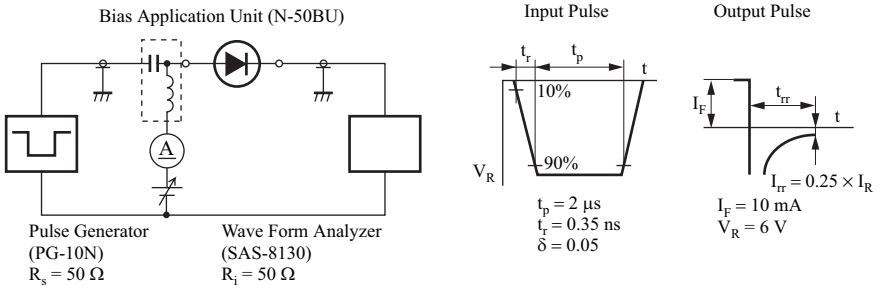
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	300	V
Repetitive peak reverse voltage	V_{RRM}	300	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Repetitive peak forward current	I_{FRM}	225	mA
Non-repetitive peak forward surge current *	I_{FSM}	500	mA
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) *: 1 t = 1 s

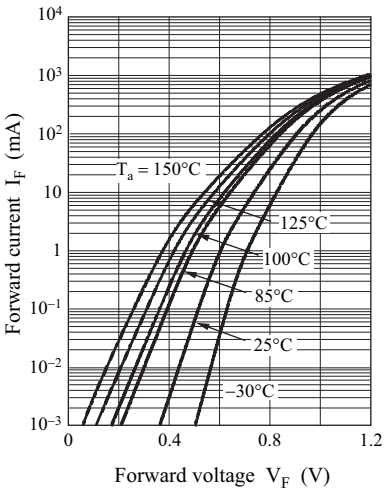
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.2	V
Reverse current	I_R	$V_R = 300$ V			1.0	μA
Terminal capacitance	C_t	$V_R = 6$ V, f = 1 MHz			3.0	pF
Reverse recovery time *	t_{rr}	$I_F = 10$ mA, $V_R = 6$ V, $I_{rr} = 0.25 \times I_R$			60	ns

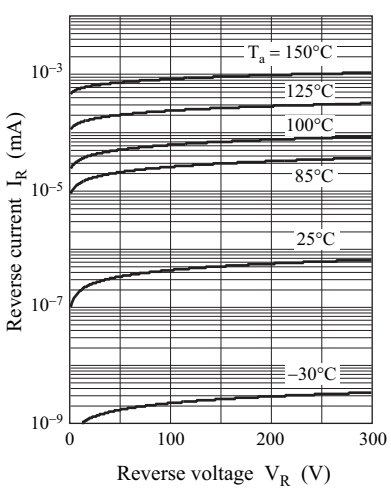
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 20 MHz
3. *: t_{rr} measurement circuit



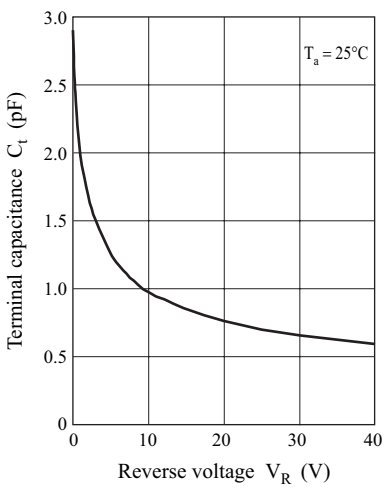
I_F — V_F



I_R — V_F

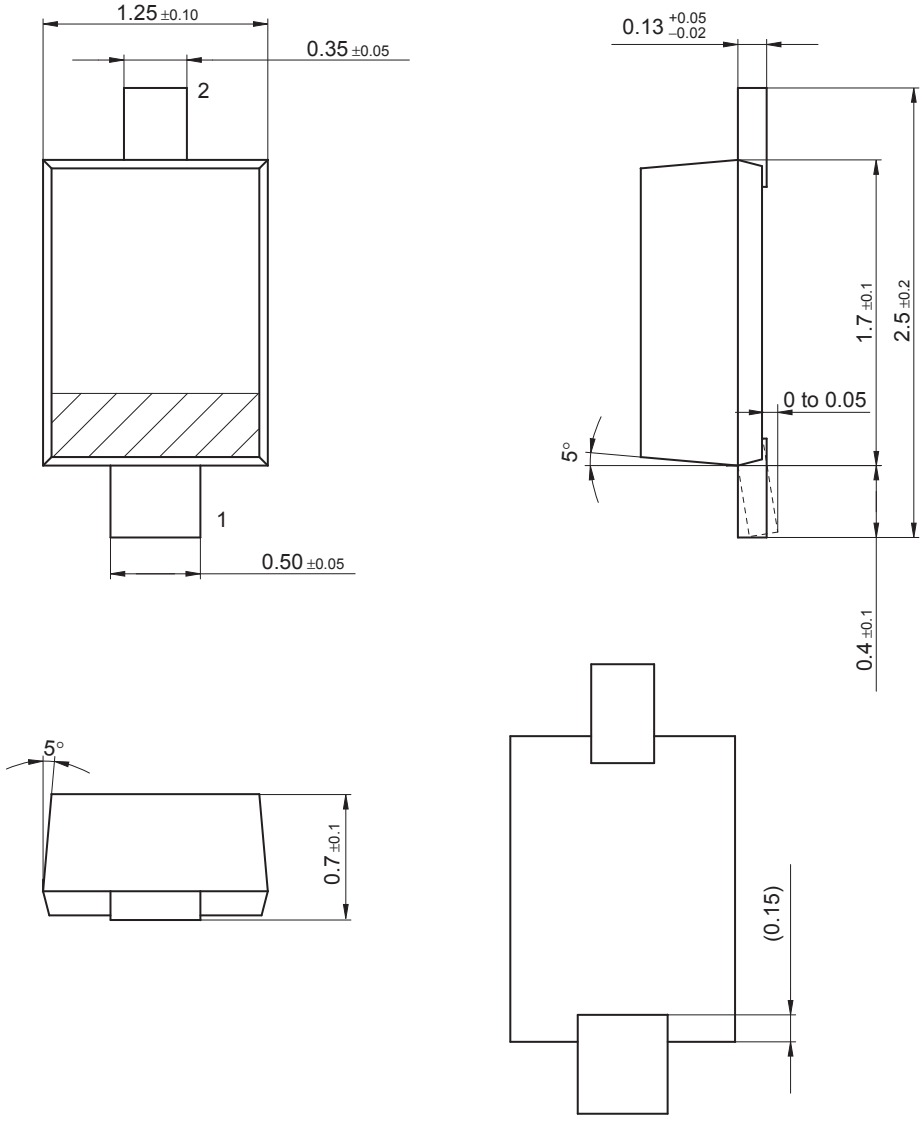


C_t — V_R



SMini2-F5-B

Unit: mm



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